



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

October 8, 2009

Applicants: Atsushi YABE et al
For: ELECTROLESS COPPER PLATING SOLUTION
Serial No.: 10/576 231 Group: 1792
Confirmation No.: 7188
Filed: April 14, 2006 Examiner: Bareford
International Application No.: PCT/JP2004/011327
International Filing Date: July 30, 2004
Atty. Docket No.: 4700.P0327US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

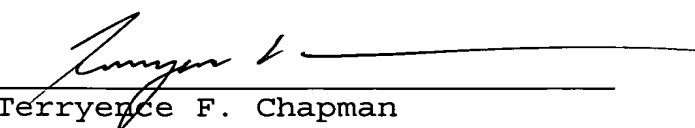
Sir:

In response to the Office Action dated July 17, 2009,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on October 8, 2009.


Terryence F. Chapman